

Special Issue

Integrated Fabrication Approaches for Soft Robotics

Message from the Guest Editors

Dear colleagues, Soft robotics is considered the new frontier of Robotics; the substantiation of this expectation requires the convergence of different scientific and technological approaches including additive fabrication, polymer actuation, soft electronics, energy storage and harvesting, neuromorphic stimuli and data handling, and edge computing. This Special Issue aims to gather high-quality research contributions dealing with the integration of different technologies to obtain disruptive structural and functional solutions for soft robotics systems.

Guest Editors

Dr. Tommaso Santaniello

Interdisciplinary Centre for Nanostructured Materials and Interfaces (CIMAINA), Physics Department, University of Milan, Via Celoria 16, 20133 Milano, Italy

Prof. Dr. Paolo Milani

Physics Department, University of Milan, Via Celoria 16, 20133 Milano, Italy

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Micromachines
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
micromachines@mdpi.com

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Editor-in-Chief

Prof. Dr. Ai-Qun Liu

1. Department of Electrical and Electronic Engineering, The Hong Kong Polytechnic University, Hong Kong, China
2. School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798, Singapore

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